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# EPOXY RESIN COMPOSITION AND PHOTOSEMICONDUCTOR DEVICE USED THE SAME

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## Abstract of JP6279568

**PURPOSE:** To obtain a composition which is excellent in heat resistance, moisture resistance, and light transmittance, has been reduced in stress, and is useful as a sealing material for a photosemiconductor element by mixing an epoxy resin with an acid anhydride hardener, a curing accelerator, and a specific copolymer. **CONSTITUTION:** The composition comprises the following ingredients (A)-(D) as essential ingredients. (A) An epoxy resin, (B) an acid anhydride hardener, (C) a curing accelerator, and (D) a copolymer of an epoxidized polybutadiene and an organopolysiloxane having per molecule at least one functional group reactive with a glycidyl group and having a mol.wt. of 500-5,000. An especially preferred example of the polymer is represented by the formula, wherein X is amino, glycidyl, etc.; R1 and R2 is a 1-2C alkyl respectively; R3 and R4 is a 1-2C alkyl or phenyl respectively; R' is a hydrocarbon residue; and m and n is an integer respectively, it means m+n=3-40.

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